



October 20, 2021

To Whom It May Concern,

Corporate Name: TechnoPro Holdings, Inc.
(Code:6028, TSE First Section)
Representative: Takeshi Yagi, President, Representative Director & CEO
Contact: Toshihiro Hagiwara, Managing Director & CFO
(Tel. 03-6385-7998)

Notice Regarding Issuance of Unsecured Straight Bonds

TechnoPro Holdings, Inc. hereby announces that it has today determined the following terms and conditions for the issuance of its 1st and 2nd Series of Unsecured Straight Bonds.

	TechnoPro Holdings, Inc. 1st Series Unsecured Straight Bonds (with inter-bond pari passu clause)	TechnoPro Holdings, Inc. 2nd Series Unsecured Straight Bonds (with inter-bond pari passu clause)
1. Total issue amount	5 billion yen	5 billion yen
2. Denomination per bond	100 million yen	
3. Coupon rate	0.130% per annum	0.200% per annum
4. Issue price	100% of the principal amount	
5. Coupon payment date	April 26 and October 26 of each year (First coupon payment date: April 26, 2022)	
6. Maturity date	October 25, 2024 (3 years)	October 26, 2026 (5 years)
7. Issue date	October 26, 2021	
8. Underwriters	SMBC Nikko Securities Inc., Daiwa Securities Co. Ltd., and Mitsubishi UFJ Morgan Stanley Securities Co., Ltd.	
9. Fiscal agent	Sumitomo Mitsui Banking Corporation	
10. Credit rating	A- (Rating and Investment Information, Inc.)	

This press release has been prepared for the sole purpose of publicly announcing the terms and conditions of the TechnoPro Holdings, Inc.'s issuance of unsecured straight bonds and not for the purpose of soliciting investment or engaging in any other similar activities.

Note on translation

This document is provided for informational purpose only. If there are any discrepancies between this and the original, the original Japanese document prevails.